

### SFP56

TE Internal #: 2343522-7

SFP, SFP+ & zSFP+, Cage Assembly with Integrated Connector,

Data Rate (Max) 56 Gb/s, Internal/External EMI Springs, SFP28 /

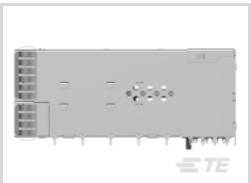
SFP56, SFP56

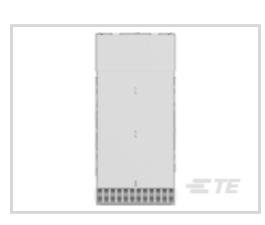
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Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+ > SFP56 Stacked Cage Assembly: EMI Spring











Pluggable I/O Product Type: Cage Assembly with Integrated Connector

Data Rate (Max): 56 Gb/s

EMI Containment Feature Type: Internal/External EMI Springs

Pluggable I/O Applications: SFP28, SFP56

Lightpipe Options: With Lightpipe

All SFP56 Stacked Cage Assembly: EMI Spring (48)

## **Features**

### **Product Type Features**

Pluggable I/O Accessory Type	Dust & EMI Cover
Form Factor	zSFP+ Stacked (SFP56)
Cage Type	Stacked
Pluggable I/O Product Type	Cage Assembly with Integrated Connector
Lightpipe Options	With Lightpipe
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Port Matrix Configuration	2 × 2
Number of Ports	4
Number of Positions	20
Electrical Characteristics	

56 Gb/s

Data Rate (Max)



#### **Termination Features**

Termination Method to Printed Circuit Board	Through Hole - Press-Fit
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.6 mm[.018 in]
Usage Conditions	
Operating Temperature Range	-55 – 105 °C[-67 – 221 °F]
Operation/Application	
Pluggable I/O Applications	SFP28, SFP56
Circuit Application	Signal
Other	
EMI Containment Feature Type	Internal/External EMI Springs

## **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

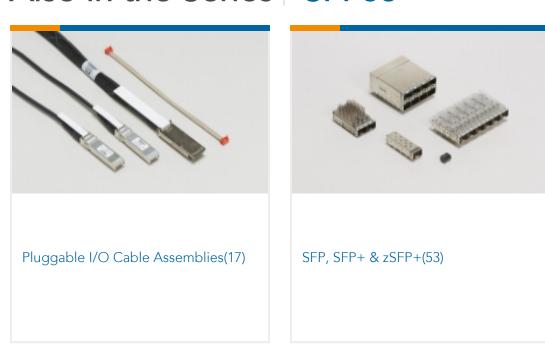


on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts



## Also in the Series | SFP56



# Customers Also Bought







## **Documents**

**CAD Files** 

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_2343522-7\_A.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2343522-7\_A.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2343522-7\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

## **Product Specifications**

**Application Specification** 

English

Product Environmental Compliance

**Product Compliance** 

English

**Product Compliance** 

English